

SID

Factory: Rot am See

Article:

ML4

Provided:

Customer:

Date:

03.04.2026

WÜRTH
ELEKTRONIK
MORE THAN
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
---------------	----------	----	---------	------------------

A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1	A00 B00
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	361		2	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		3	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		4	
C-RaS-FR4-DS-2.388mm-018+018-TG150-HF...	50203156	18	L2		
		2352		5	
		18	L3		
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	361		6	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		7	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		8	
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	9	

Thickness after Pressing

B00:

3090 µm

Tol+:

320 µm

Tol-:

320 µm

Dmax:

3410 µm

Dmin:

2770 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

3200 µm

Tol+:

320 µm

Tol-:

320 µm

Dmax:

3520 µm

Dmin:

2880 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal:

3146 µm

Version 1.2.20.35

© Würth Elektronik